



Material Content Data Sheet



Sales Product Name				SAK-TC1798F-512F300EP AB		Issued		24. January 2018	
MA#				MA001618444					
Package				PG-LFBGA-516-8		Weight*		1986.55 mg	
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	31.392	1.58	1.58	15802	15802	
wire	noble metal	palladium	7440-05-3	0.023	0.00		12		
	non noble metal	copper	7440-50-8	2.308	0.12	0.12	1162	1174	
encapsulation	organic material	carbon black	1333-86-4	1.689	0.08		850		
	plastics	epoxy resin	-	116.533	5.87		58661		
	inorganic material	silicondioxide	60676-86-0	726.222	36.58	42.53	365571	425082	
substrate	inorganic material	bariumsulfate	7727-43-7	23.317	1.17		11737		
	plastics	acrylic resin	-	26.985	1.36		13584		
	inorganic material	Metal Hydroxide	-	32.274	1.62		16246		
	inorganic material	silicondioxide	60676-86-0	102.202	5.14		51447		
	plastics	epoxy resin	-	192.704	9.70		97005		
	inorganic material	glass fibre	-	225.920	11.37		113725		
	non noble metal	copper	7440-50-8	248.966	12.53	42.89	125326	429070	
plating	noble metal	gold	7440-57-5	0.638	0.03		321		
	non noble metal	nickel	7440-02-0	1.747	0.09	0.12	879	1200	
solderball	noble metal	silver	7440-22-4	8.700	0.44		4379		
	non noble metal	tin	7440-31-5	239.863	12.07	12.51	120744	125123	
glue	plastics	epoxy resin	-	1.266	0.06		637		
	noble metal	silver	7440-22-4	3.797	0.19	0.25	1912	2549	
*deviation	< 10%					Sum in total:	100.00	1000000	

Important Remarks:

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This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com